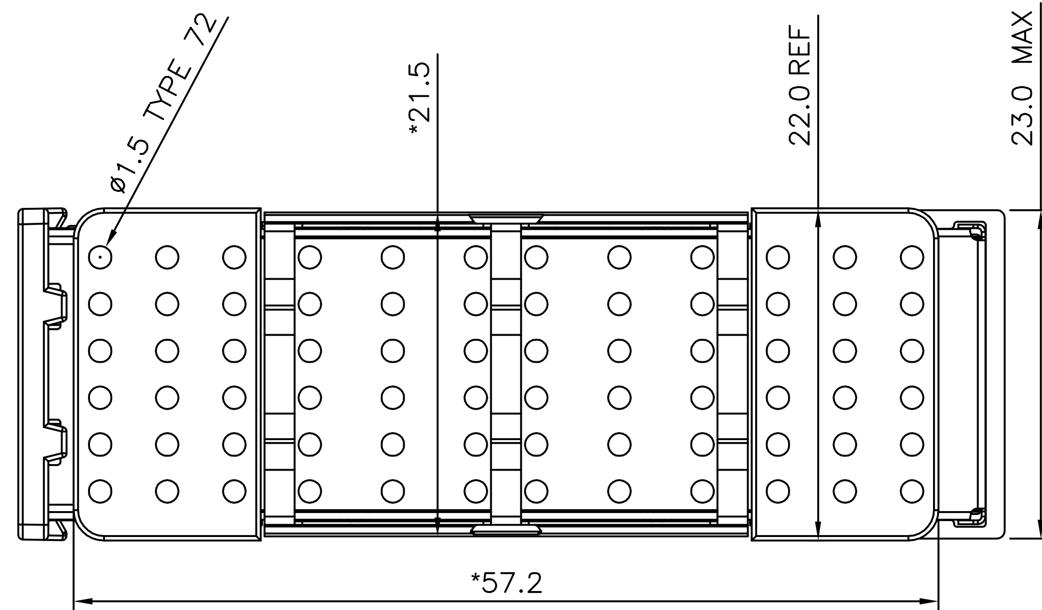
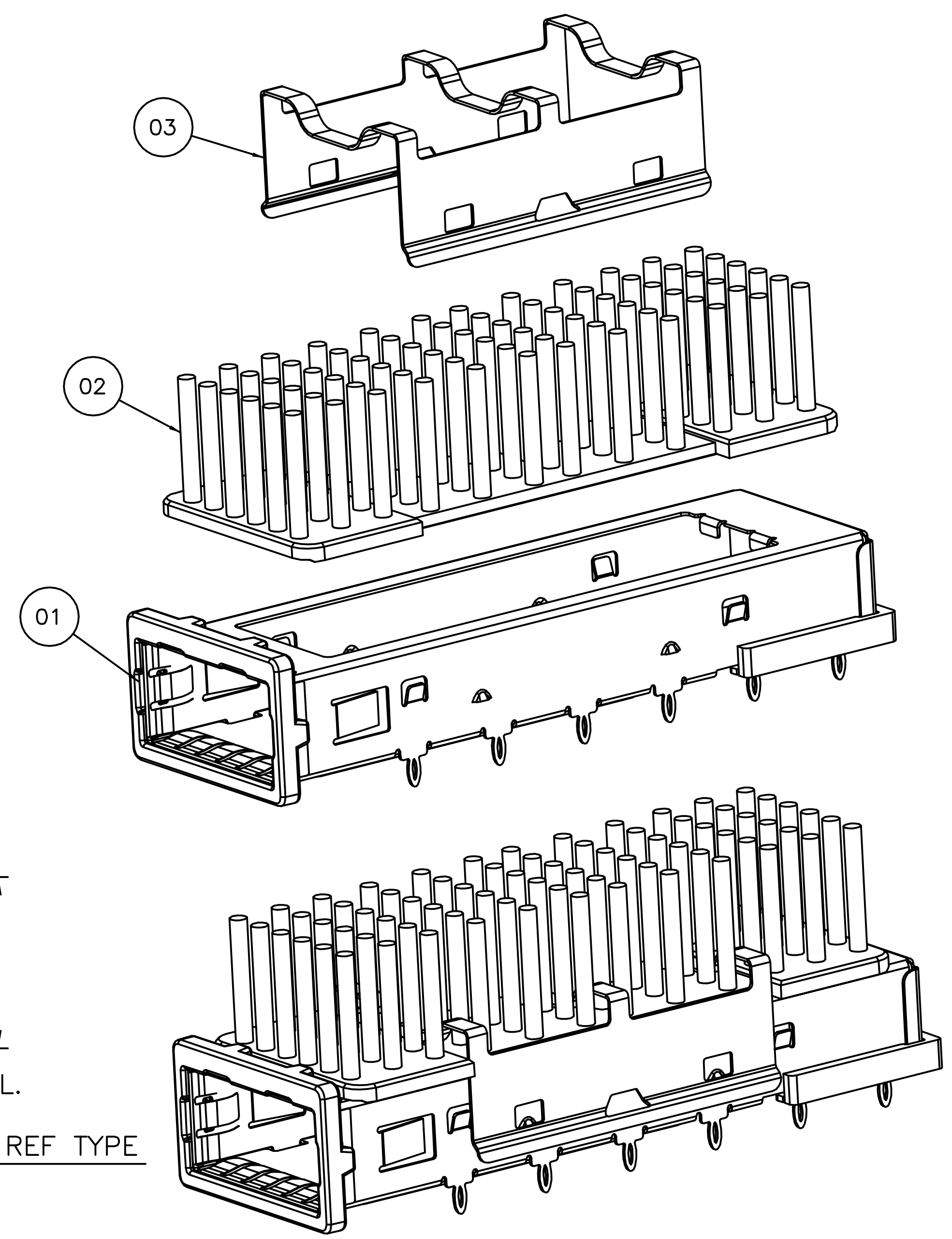
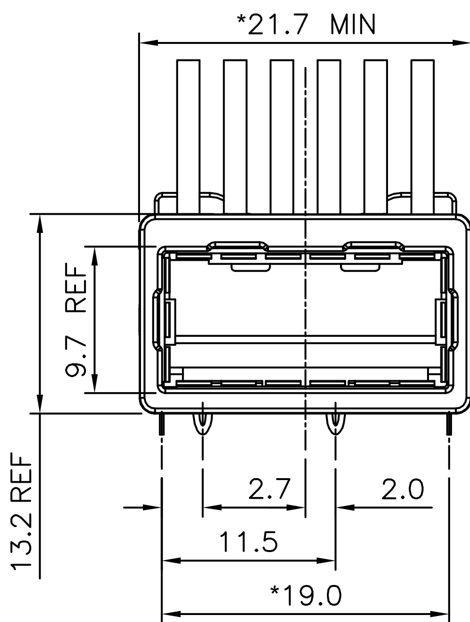
A1RFRD10

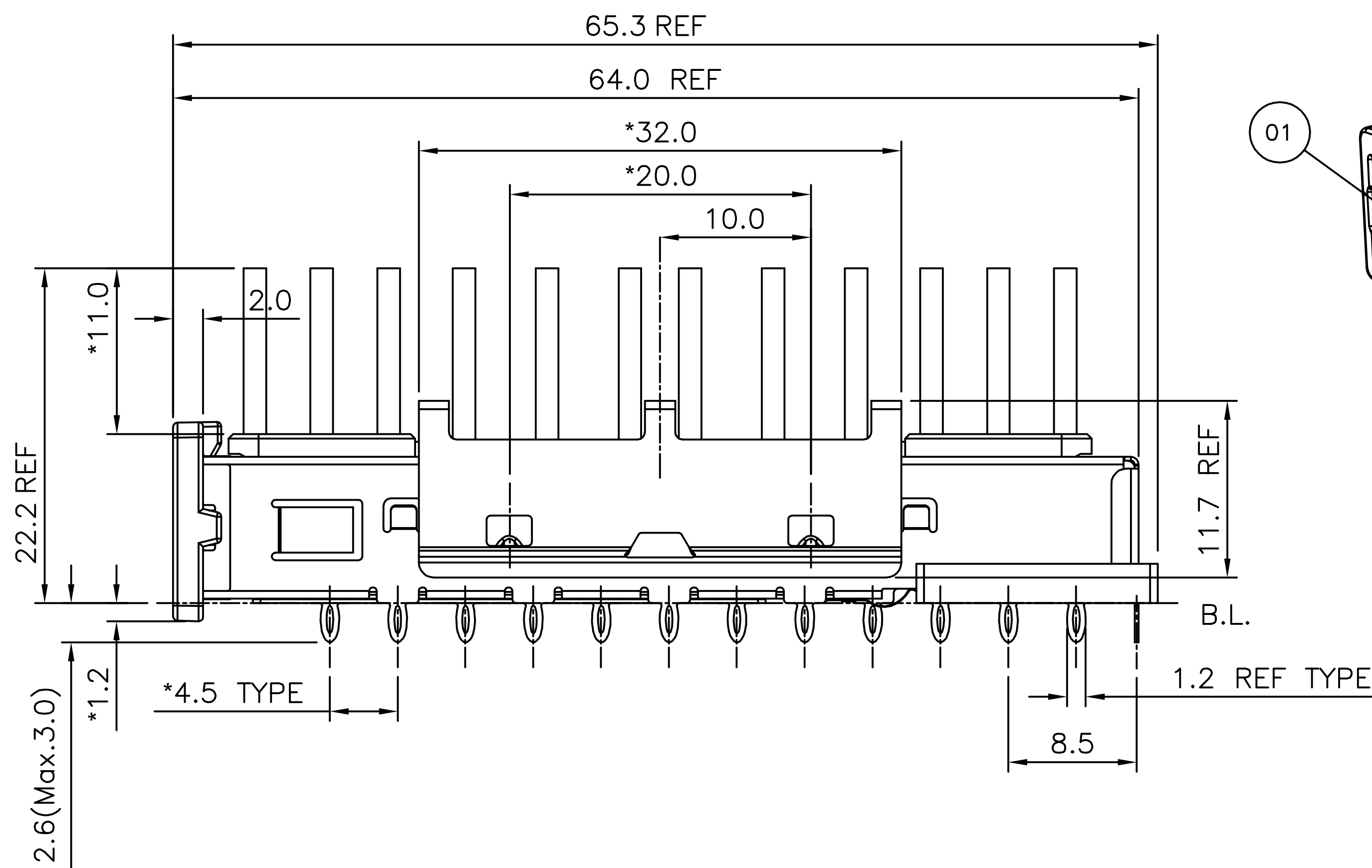
REV	ECO	DESCRIPTION	DRFT	CHKD

REVISION RECORD









PART NUMBER: XFP003-L

No.	DESCRIPTION	Q'ty	MATERIAL	PLATING	REMARK
01	XFP CAGE ASSEMBLY (Non-Logo)	1			
02	XFP HEAT SINK (11.00mm)	1	AL	Ni	
03	XFP HEAT SINK CLIP	1	SUS		

MM (INCH)		DFTO tzou	DATE 06/02/06'
TOLERANCES EXCEPT AS NOTED		CHKD	DATE
MM		MFO	DATE
.0 ± 0.2	±	APPVL	DATE
.00 ± 0.15	±	MATERIAL :	
.000 ± 0.075	±		
ANGLES ± 0.5		QT'Y :	
THIRD ANGLE PROJECTION		FINISH :	
		SCALE : 1 : 2	

DETACHED LISTS

FULL RISE ELECTRONIC CO., LTD

TITLE (Non-Logo)

XFP CAGE WITH PCI HEAT SINK KIT

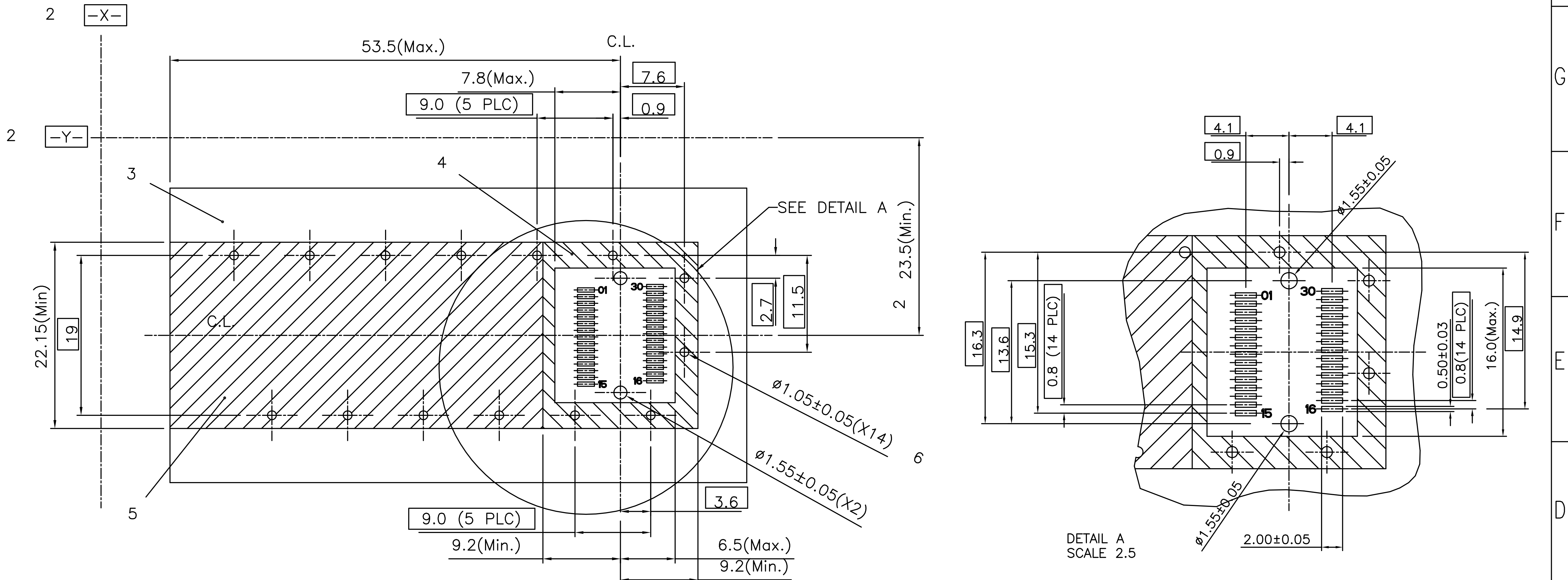
DRAWING NO. XFP003-L	SIZE	REV
/PART NO. SEE NOTE	A3	0
DO NOT SCALE DRAWING	SHEET 1 OF 2	

8 7 6 5 4 3 2 1

H G F E D C B A

A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT

Note:

1 DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).

2 DATUM -X- AND -Y- ESTABLISHED BY CUSTOMER.

3 DATUM -A- IS TOP SURFACE OF HOST BOARD.

4 INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.

5 CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

6 RECOMMENDATION FOR P.C.BOARD HOLES:
A. HOLE Ø AFTER DRILLING : 1.15±0.02 mm.
B. HOLE Ø Sn PLATE : 1.05±0.05 mm.
C. 25um ~ 50um COPPER UNDERPLATE.

7 -CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.

DETACHED LISTS	MM (INCH)		DFTO tzou	DATE 06/02/06'	FULL RISE ELECTRONIC CO., LTD		
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE			
	MM		MFO	DATE			
	.0 ± 0.2	±	APPVL	DATE	TITLE (Non-Logo)		
	.00 ± 0.15	±			XFP CAGE WITH PCI HEAT SINK KIT		
	.000 ± 0.075	±	MATERIAL :				
	ANGLES ± 0.5		QT'Y :		DRAWING NO. XFP003-L	SIZE	REV
			FINISH :		/PART NO. SEE NOTE	A3	0
	THIRD ANGLE PROJECTION		SCALE : 1 : 2		DO NOT SCALE DRAWING	SHEET 2	OF 2

8 7 6 5 4 3 2 1
H G F E D C B A